

FQB13N06 / FQI13N06

60V N-Channel MOSFET

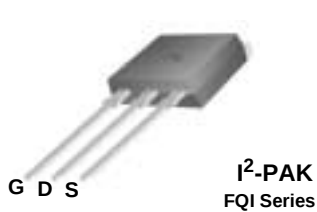
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as DC/DC converters, high efficiency switching for power management in portable and battery operated products.

Features

- 13A, 60V, $R_{DS(on)} = 0.135\Omega$ @ $V_{GS} = 10\text{ V}$
- Low gate charge (typical 5.8 nC)
- Low C_{rss} (typical 15 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQB13N06 / FQI13N06	Units
V_{DSS}	Drain-Source Voltage	60	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	13	A
	- Continuous ($T_C = 100^\circ\text{C}$)	9.2	A
I_{DM}	Drain Current - Pulsed (Note 1)	52	A
V_{GSS}	Gate-Source Voltage	± 25	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	85	mJ
I_{AR}	Avalanche Current (Note 1)	13	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	4.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	7.0	V/ns
P_D	Power Dissipation ($T_A = 25^\circ\text{C}$) *	3.75	W
	Power Dissipation ($T_C = 25^\circ\text{C}$)	45	W
	- Derate above 25°C	0.3	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	3.35	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *	--	40	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.5	$^\circ\text{C/W}$

* When mounted on the minimum pad size recommended (PCB Mount)

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	60	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C	--	0.06	--	V/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
		$V_{DS} = 48\text{ V}, T_C = 150^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 25\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -25\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 6.5\text{ A}$	--	0.105	0.135	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 25\text{ V}, I_D = 6.5\text{ A}$ (Note 4)	--	5.1	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	240	310	pF
C_{oss}	Output Capacitance		--	90	120	pF
C_{rss}	Reverse Transfer Capacitance		--	15	20	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 30\text{ V}, I_D = 6.5\text{ A},$ $R_G = 25\text{ }\Omega$	--	5	20	ns
t_r	Turn-On Rise Time		--	25	60	ns
$t_{d(off)}$	Turn-Off Delay Time		--	8	25	ns
t_f	Turn-Off Fall Time	(Note 4, 5)	--	15	40	ns
Q_g	Total Gate Charge	$V_{DS} = 48\text{ V}, I_D = 13\text{ A},$ $V_{GS} = 10\text{ V}$	--	5.8	7.5	nC
Q_{gs}	Gate-Source Charge		--	2.0	--	nC
Q_{gd}	Gate-Drain Charge		--	2.5	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	13	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	52	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 13 A	--	--	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 13 A,	--	39	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs (Note 4)	--	40	--	nC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 590\text{ }\mu\text{H}$, $I_{AS} = 13\text{ A}$, $V_{DD} = 25\text{ V}$, $R_G = 25\text{ }\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 13\text{ A}$, $di/dt \leq 300\text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\text{ }\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

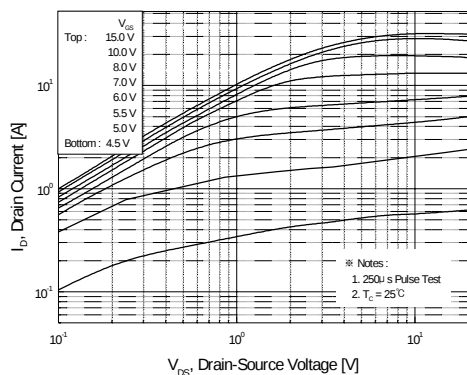


Figure 1. On-Region Characteristics

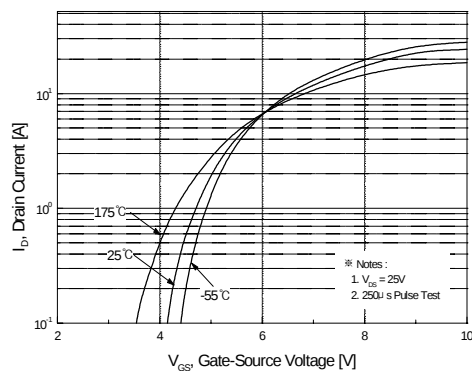


Figure 2. Transfer Characteristics

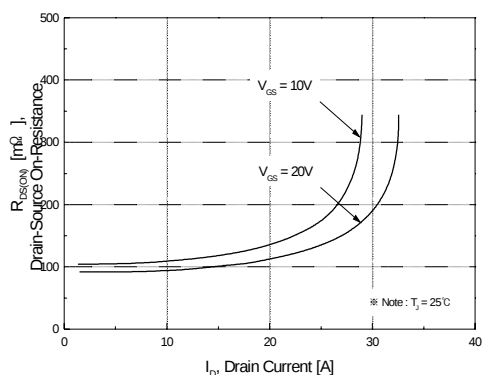


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

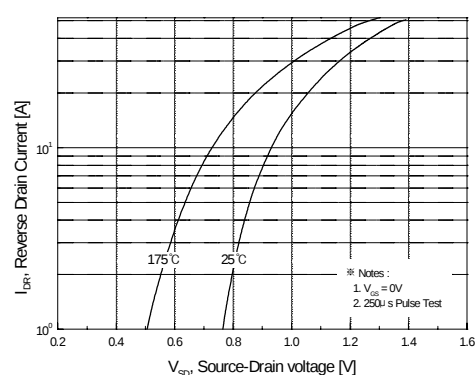


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

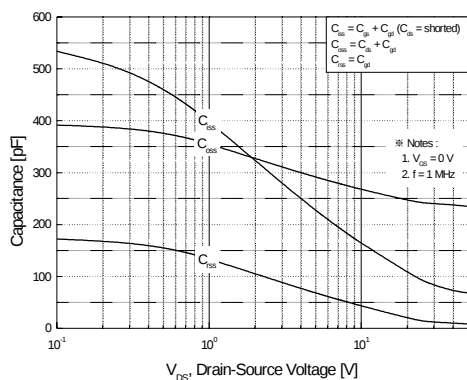


Figure 5. Capacitance Characteristics

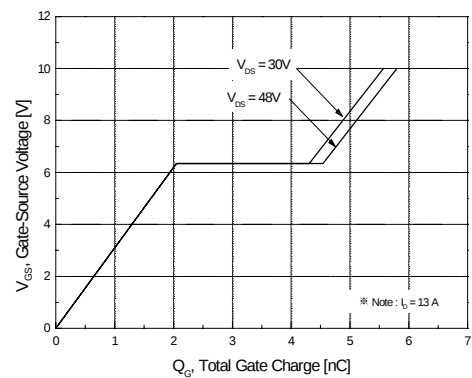


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

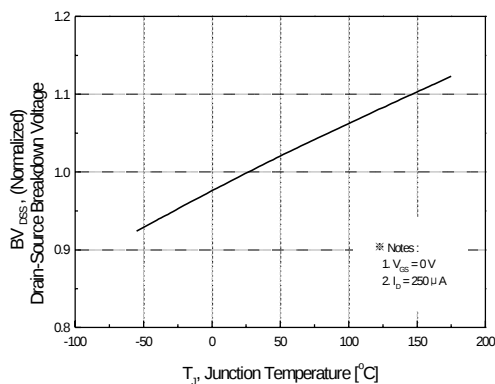


Figure 7. Breakdown Voltage Variation vs. Temperature

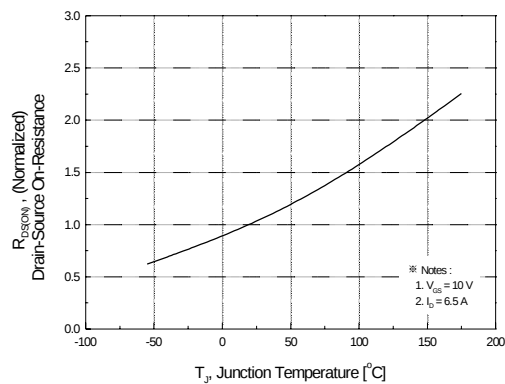


Figure 8. On-Resistance Variation vs. Temperature

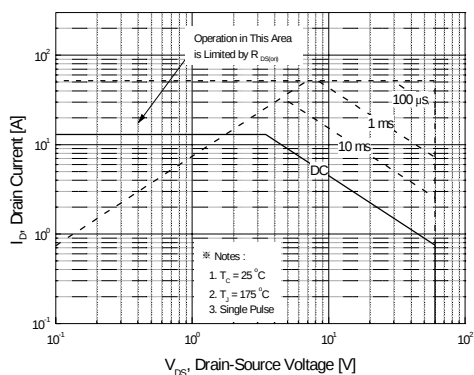


Figure 9. Maximum Safe Operating Area

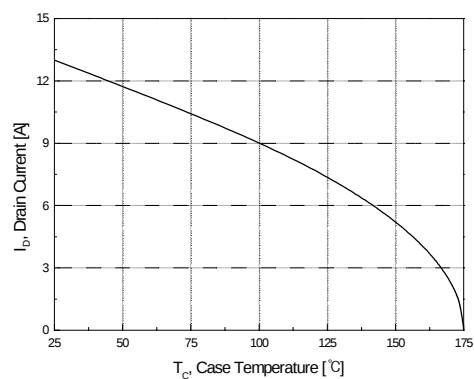


Figure 10. Maximum Drain Current vs. Case Temperature

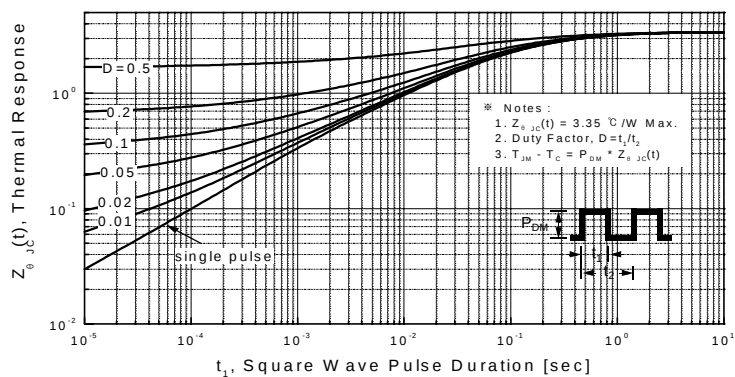


Figure 11. Transient Thermal Response Curve

Gate Charge Test Circuit & Waveform



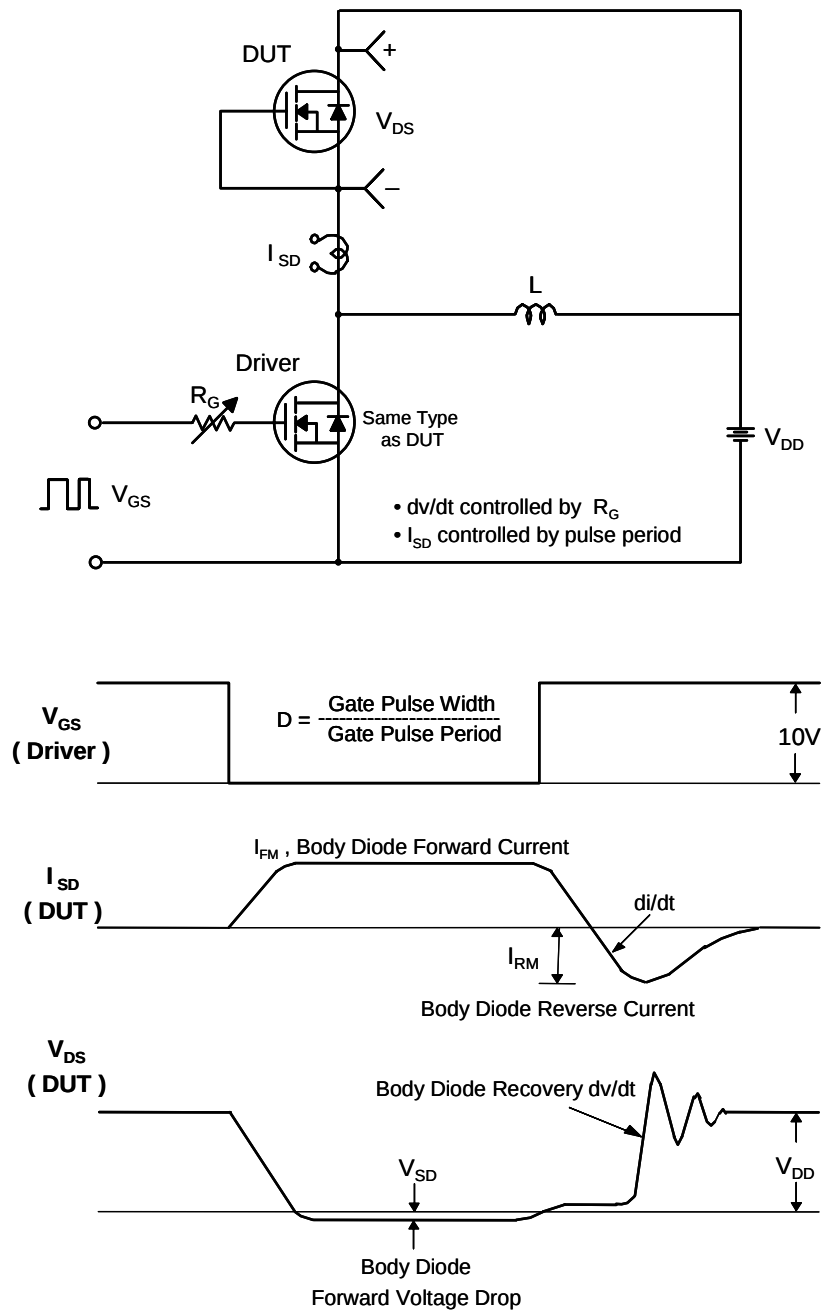
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms



FQB13N06 / FQI13N06

Technical drawing of a 1.5A 12VDC 100mA 1000Hz piezo buzzer, showing four views with dimensions in millimeters (mm) and tolerances.

Top View:

- Overall width: 9.90 ± 0.20
- Overall height: 15.30 ± 0.30
- Top flange width: 1.40 ± 0.20
- Top flange height: 0.40
- Central circular feature diameter: 1.20 ± 0.20
- Bottom mounting tab width: 1.27 ± 0.10
- Bottom mounting tab spacing: 2.54 TYP
- Bottom mounting tab width: 0.80 ± 0.10

Side View:

- Overall width: 4.50 ± 0.20
- Top flange height: $1.30^{+0.10}_{-0.05}$
- Body height: 2.00 ± 0.10
- Body width: 0.10 ± 0.15
- Bottom mounting tab width: 2.40 ± 0.20
- Bottom mounting tab spacing: 2.54 ± 0.30
- Bottom mounting tab width: $0.50^{+0.10}_{-0.05}$
- Bottom mounting tab height: 0.75
- Bottom mounting tab angle: $0^\circ - 3^\circ$

Front View:

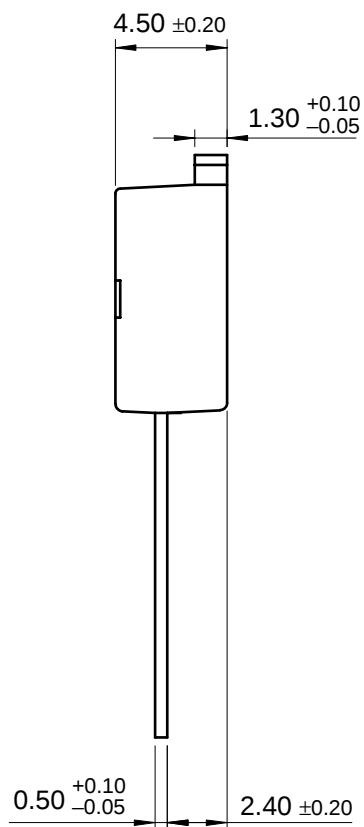
- Overall width: 10.00 ± 0.20

Bottom View:

- Overall width: 10.00 ± 0.20
- Overall height: 15.30 ± 0.30
- Top flange width: 10.00 ± 0.20
- Top flange height: 1.75
- Body width: 8.00
- Body height: 7.20
- Body width (inner): 4.40
- Body height (inner): 9.20 ± 0.20
- Body width (inner, rounded): $(2 \times R0.45)$
- Bottom mounting tab width: 0.80 ± 0.10
- Bottom mounting tab spacing: 2.54 TYP
- Bottom mounting tab width: 0.80 ± 0.10

Package Dimensions (Continued)

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